

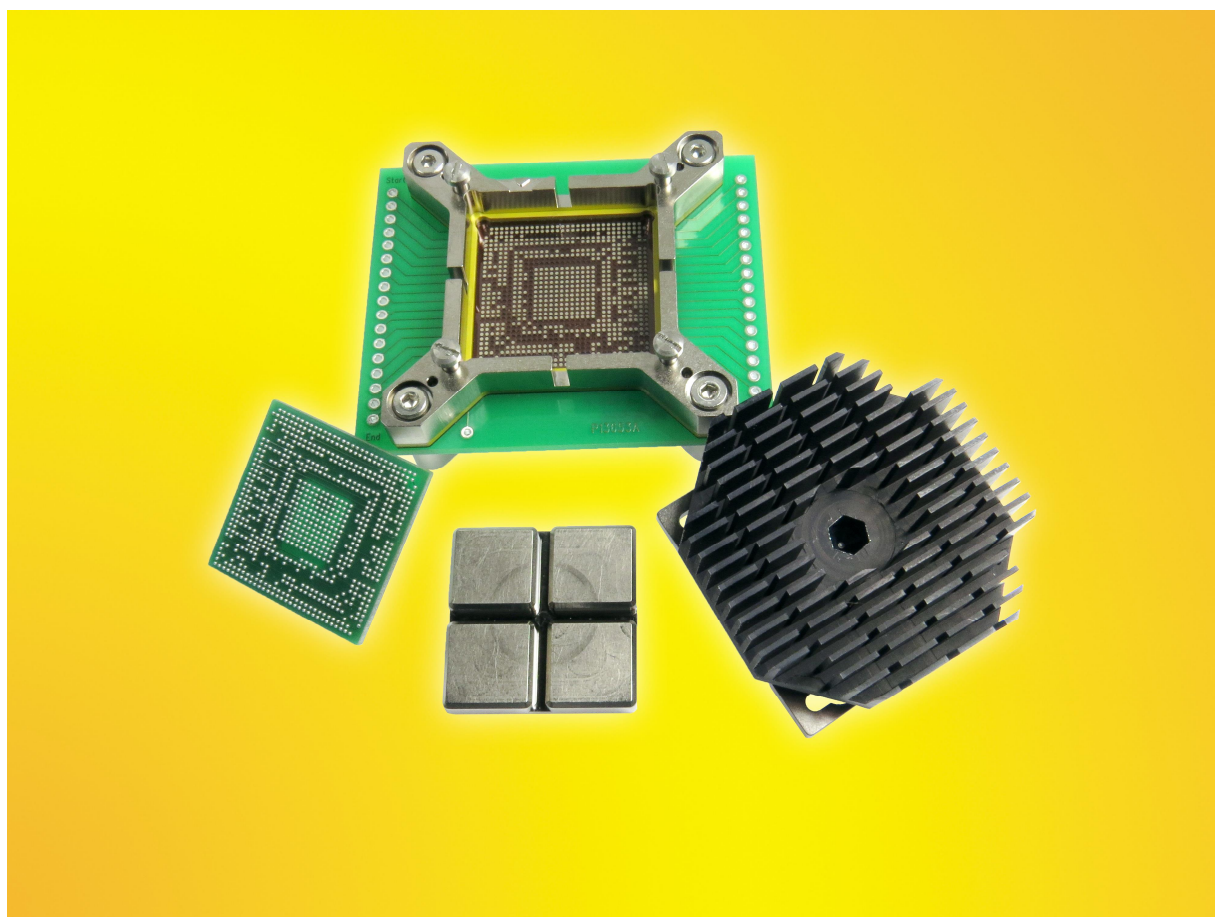


Ironwood
ELECTRONICS

75 GHz Bandwidth Heat Sink Lid Socket for BGA715

Quickly and easily Socket your 27x27mm, 0.8mm pitch BGA packages on any application board with performance equivalent to direct solder version

EAGAN, MN - October, 2014 - Ironwood Electronics has recently introduced a new BGA socket design using high performance elastomer capable of 75 GHz, very low inductance and wide temperature applications. The GT-BGA-6008 socket is designed for 27x27 mm package size and operates at bandwidths up to 75 GHz with less than 1dB of insertion loss. The socket is designed to dissipate 4.5 watts using compression screw with heat sink fins and can be customized up to 100 watts with modified fin design on top of the screw and adding axial flow fan. The contact resistance is typically 20 milliohms per pin. The socket is mounted on the target PCB with no soldering, and uses very small real estate allowing capacitors/resistors to be placed close by. The socket is constructed with swivel lid which incorporates a quick insertion method so that IC's can be changed out quickly. The socket has center opening for thermocouple and thermal streaming. Compression plate has channels for thermal stream out.



The GT-BGA-6008 socket is constructed with high performance and low inductance elastomer contactor. The temperature range is -55 C to +160 C. Works with IC's such as BGA, 27x27mm with 32x32 array and 0.8mm pitch.

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B.C.E. S.r.l. - Via Regina Pacis, 54/c - I 41049 Sassuolo (MO), Italy

Tel: (+39) 0536 811616

Fax: (+39) 0536 811500

E-mail: bce@bce.it

Web: www.bce.it